

## **Q7700 Automatic Gold Ball Bonder**

**Designed for Complex Hybrid, Opto-Electronic and I.C. Assembly Requirements**

### **Specifications\***

#### **Standard Features – Hardware**

4" x 4" Bond Area  
Programmable Temperature Controller  
Programmable U/S Generator  
Solid State Vision System  
Pattern Recognition System  
Flat Panel Monitor  
Wireless Mouse  
Stereo Zoom 4 Microscope  
Galil Motion Control System  
Windows XP™ OS  
Fiber Optic Light Source

#### **Specifications**

Gold Wire  
Size Range  
0.0008" – 0.002" (20 – 51 microns)  
Maximum Wires per Device  
Unlimited

Bonding Speed per Wire  
500 ms pending application

XY Table  
Resolution  
± 0.0000625" (1.6 microns)  
Bonding Pitch  
± 0.00275" (69.9 microns)

#### **Options**

Custom Software  
Heated Universal Workholder  
Additional Fiber Optic Light Source

#### **Standard Features – Software**

Point and Click Bond Targeting  
Simple, Intuitive Programming  
Easy Bond Process Editing  
Extensive Program Storage  
Bond Parameter Library  
Unlimited Wire Program Storage  
Program Wire Groups for Multi Device,  
High Wire Count Hybrids  
Ball / Stud Bumping and Coining  
SoS Bonding (Stitch on Stud bump)  
Security Bond

#### **Accessories**

Ethernet Adapter for Networking Bonders

#### **Miscellaneous**

Remote Diagnostics Capability  
CE Mark

#### **Facilities**

Electric - 120 VAC, 50/60 Hz, 15A  
N2 or clean, dry air  
Vacuum / Air as required for workholder

#### **Dimension/Weight**

Height: 72" (183 cm)  
Width: 39" (99 cm)  
Depth: 34.5" (88 cm)  
Table Height: 40" (102 cm)  
Weight: 525 pounds (227 Kg)  
Crated Weight: 700 pounds (306 Kg)

\* Subject to Change

12/01/14